

Title (en)

Method and apparatus for degassing semiconductor processing liquids.

Title (de)

Verfahren und Vorrichtung zum Entgasen einer Flüssigkeit zum Herstellen einer Halbleiter.

Title (fr)

Procédé et dispositif de dégazage d'un liquide de fabrication de semi-conducteurs.

Publication

EP 0622475 A1 19941102 (EN)

Application

EP 94302468 A 19940407

Priority

US 5704293 A 19930429

Abstract (en)

The disclosure relates to a degasser for removing gas entrapped or dissolved in a semiconductor wafer processing liquid consisting of a housing (62) and a fluid inlet/outlet (22) through which the processing liquid is passed respectively into and out of the housing. The degasser includes a separator (68) in the form of a circular pipe defining a tortuous (preferably spiral) path for the processing fluid as it passes through the housing. The separator is configured to be pervious to the molecules of the entrapped or dissolved gas but impervious to the molecules of the liquid. The degasser also includes a port (66) through which the housing (62) can be evacuated thereby resulting in a pressure differential across the separator. This causes molecules of the entrapped or dissolved gas to leave the liquid and to permeate through the separator and thus removing the gas from the processing liquid. <IMAGE>

IPC 1-7

C23C 16/44; **B01D 19/00**

IPC 8 full level

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CPC (source: EP)

B01D 19/0031 (2013.01); **B01D 19/0036** (2013.01); **C23C 16/4402** (2013.01); **C23C 16/4485** (2013.01)

Citation (search report)

- [YA] EP 0434966 A1 19910703 - CORNING INC [US]
- [A] US 4549889 A 19851029 - YAMAZAKI SHUNPEI [JP]
- [XAY] PATENT ABSTRACTS OF JAPAN vol. 010, no. 389 (P - 531) 26 December 1986 (1986-12-26)
- [YA] PATENT ABSTRACTS OF JAPAN vol. 012, no. 433 (C - 543) 15 November 1988 (1988-11-15)

Cited by

CN109107227A; EP1021588A4; GB2303564A; GB2303564B; US7615104B2; US6939392B2; US7569099B2; US7687110B2; US7393388B2; US7582137B2; WO2005080630A1; US7465336B2; US7377112B2; US7435283B2; US7824470B2

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